

Stanford



Pingyu Wang

Postdoctoral Scholar, Chemical Engineering

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Pingyu is a postdoctoral scholar in the Tarpeh Lab at Stanford University, where he develops low-cost, continuous sensing technologies for environmental monitoring. His current research focuses on multiplex detection of reactive nitrogen species to improve nitrogen management in agriculture and wastewater treatment.

Pingyu earned his PhD in Materials Science and Engineering at Stanford, where he developed high-density neural interfaces for retinal prostheses aimed at vision restoration. Drawing on his background in bioelectronics and sensor design, he is interested in advancing sensing technologies to support data-driven solutions for environmental challenges.

STANFORD ADVISORS

- William Tarpeh, Postdoctoral Faculty Sponsor

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